2SA2028G

Silicon PNP epitaxial planar type

For DC-DC converter

Features

- \bullet Low collector-emitter saturation voltage $V_{CE(sat)}$
- High-speed switching
- S-Mini type package, allowing downsizing and thinning of the equipment and automatic insertion through the tape packing
- Package
- Code
- SMini3-F2
- Marking Symbol: AT
- Pin Name
 - 1. Base
 - 2. Emitter
 - 3. Collector

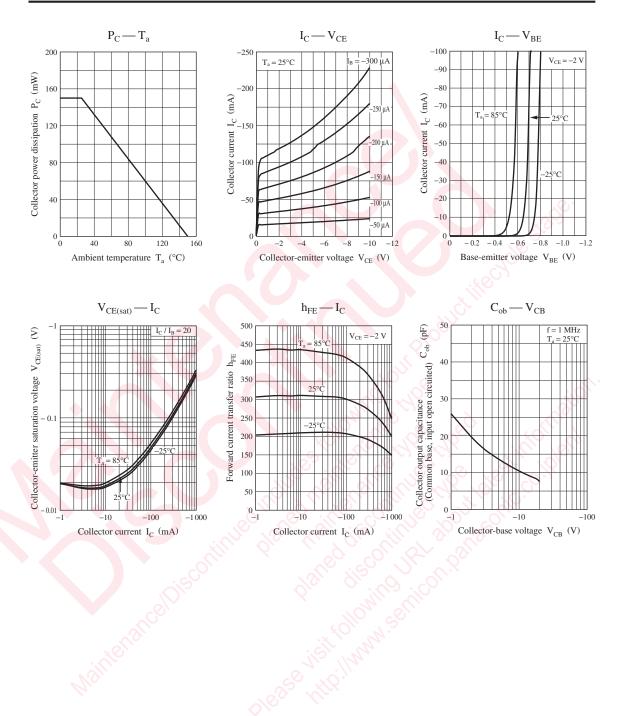
Absolute Maximum Ratings $T_a = 25^{\circ}C$

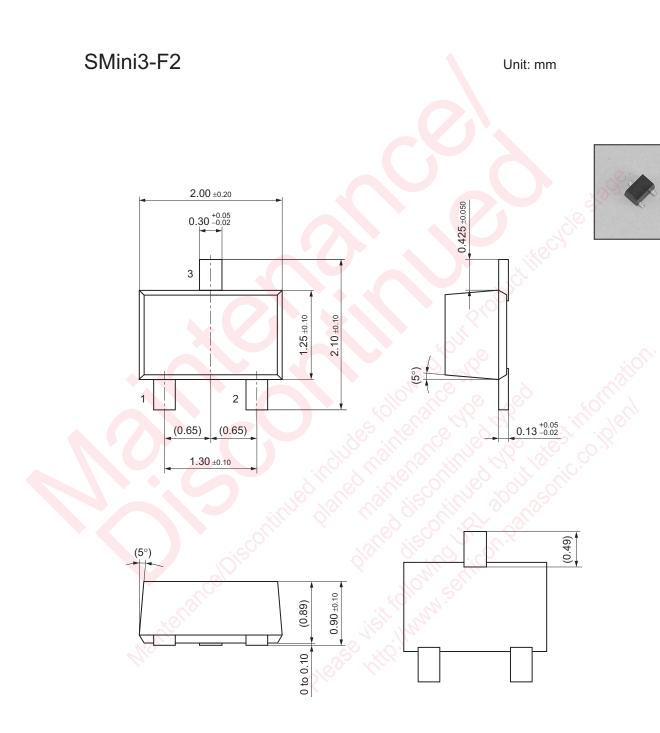
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-20	V
Collector-emitter voltage (Base open)	V _{CEO}	-20	v
Emitter-base voltage (Collector open)	V _{EBO}	-5	V
Collector current	I _C	-1	А
Peak collector current	I _{CP}	-3	A
Collector power dissipation	P _C	150	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu A, I_{\rm E} = 0$	-20			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-20			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = -10 \ \mu A, I_{\rm C} = 0$	-5			V
Forward current transfer ratio	h _{FE}	$V_{CE} = -2 \text{ V}, I_C = -100 \text{ mA}$	160		560	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -200 \text{ mA}, I_{\rm B} = -10 \text{ mA}$		-40	-100	mV
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		170		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		20	30	pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





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